



Data Sheet

Customer:	
Part No:	CL-SP192PP-02
Sample No:	
Description:	1608 SMD Pink Color
Item No:	

Customer						
Check Inspection Approval Date						





handling electrostatic discharge sensitive devices 接触静电放电敏感元件时 请采取适当的预防措施

ENTION

意 ESD protected area 静电防护区域 Observe precautions for

注

Features

_1.6mmX0.8mm SMT LED, 0.60mm THICKNESS. LOW POWER CONSUMPTION. _WIDE VIEWING ANGLE. _IDEAL FOR BACKLIGHT AND INDICATOR. _VARIOUS COLORS AND LENS TYPES AVAILABLE. _PACKAGE: 4000 PCS / REEL. _RoHS COMPLIANT.

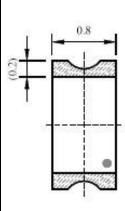
Description

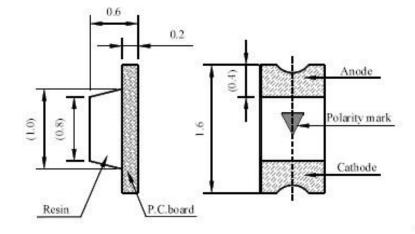
The Pink source color devices are made with

Gallium

Arsenide Phosphide on Gallium Phosphide Pink Light

Package Dimensions





Unit: mm Tolerance:±0.1

Notes:

1. All dimensions are in millimeters (inches).

2. Tolerance is $\pm 0.1(0.004")$ unless otherwise noted.

3. Specifications are subject to change without notice.





Selection Guide

Part No.	Dice	Lens Type		(mcd) 5mA	Viewing Angle	
			Min.	MAX.	2 θ 1/2	
CL-SP192PP-02	Pink (GaN)	PINK Diffused	57	140	120	

Note:

1. $\theta 1/2$ is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λD	Dominant Wavelength	Pink			nm	IF=5mA
Δλ1/2	Spectral Line Half-width	Pink			nm	IF=5mA
С	Capacitance	Pink			рF	VF=0V;f=1MHz
VF	Forward Voltage	Pink	2.7	3.1	v	IF=5mA
IR	Reverse Curren	Pink		2	uA	VR =5V

Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity, or wavelength), the typical

accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm

2. Luminous Intensity: +/-15%

3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters

Absolute Maximum Ratings at TA=25°C

Parameter	Pink	Units
Power dissipation	135	mW
DC Forward Current	20	mA
Peak Forward Current [1]	100	mA
Reverse Voltage	5	V
Operating/Storage Temperature	-40°C To +85°C	·

Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.



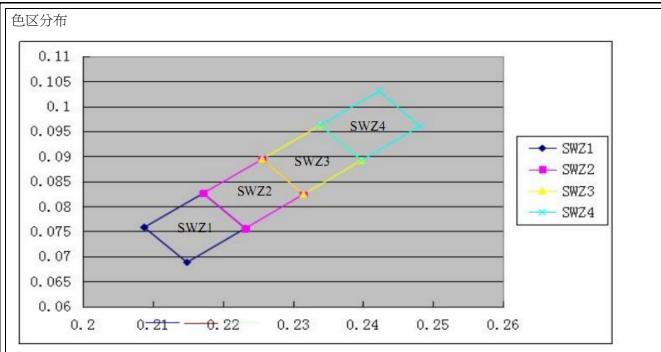


Test condition: @5mA					
BIN Code	V _{Fmin} (v)	V _{Fmax} (v)			
1	2.7	2.8			
2	2.8	2.9			
3	2.9	3.0			
4	3.0	3.1			

Test condition: @5mA					
BIN Code	I _{Vmin} (mcd)	I _{Vmax} (mcd)			
P2	57	72			
Q1	72	90			
Q2	90	112			
R1	112	140			





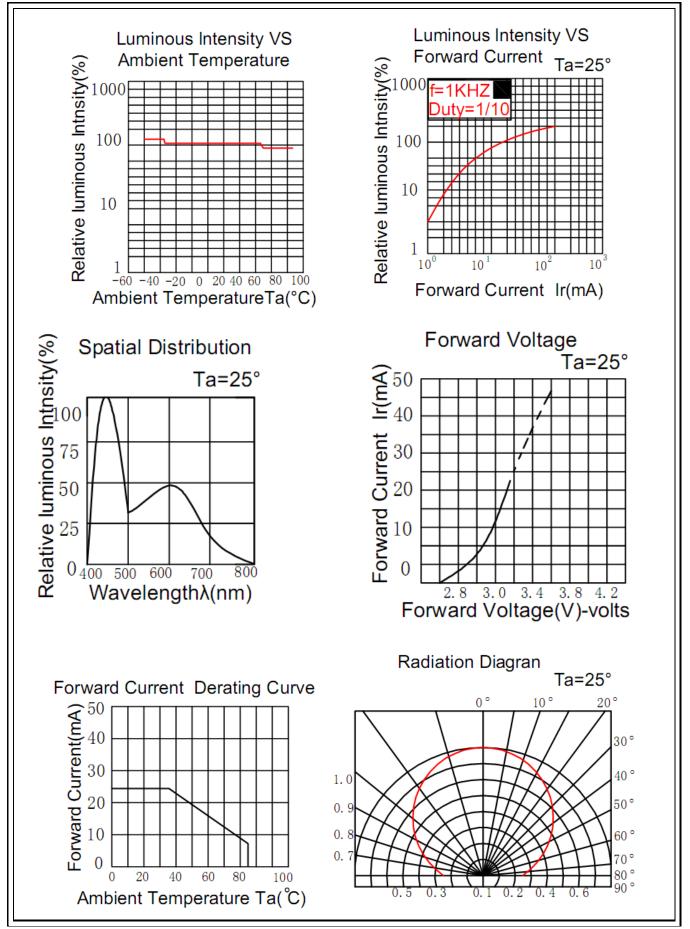


色区坐标:

序号	X1	¥1	X2	¥2	X3	¥3	X4	Y4	X5	Y5
SWZ1	0.2088	0.0758	0.2149	0.0688	0. 2232	0. 0756	0.2172	0.0826	0.2088	0. 0758
SWZ2	0.2172	0.0826	0.2232	0.0756	0. 2315	0. 0824	0.2256	0.0894	0.2172	0. 0826
SWZ3	0. 2256	0.0894	0.2315	0.0824	0.2398	0. 0892	0.2339	0.0962	0.2256	0. 0894
SWZ4	0.2339	0.0962	0.2398	0.0892	0.2481	0.096	0.2423	0. 103	0.2339	0.0962











RELIABILITY

(1) TestItemsandResults

NO.	Test Item	Reference Standard	Test Conditions	(Hours/ Cycles)	Sampl e	Number of Damaged
1	Temperature Cycle	JEITA ED-4701	-40 °C - 25 °C - 100 °C - 25 °C 30min 5min 30min 5min	100 Cycl es	20	0/50
2	Thermal shock	MIL-STD-202G	-40℃~100℃ 15min 15min	500 Cycl es	20	0/50
3	High Temperature Storage	JEITA ED-4701 200 201	Ta=100℃	1000 Hours	20	0/50
4	Low Temperature Storage	JEITA ED-4701 200 201	Ta=-40°C	1000 Hours	20	0/50
5	Room Temperature Life Test		Ta=25±5℃ IF=20mA	1000 Hours	20	0/50
6	High Temperature High Humidity Life Test		Ta=60℃ RH=85% IF=20mA	1000 Hours	20	0/50
7	Sol derability (Reflow Sol dering)	JEITA ED-4701 300 303	Tsol=235°C \pm 5°C,5sec (Using Flux, Lead Solder)	1 time, 5sec	10	0/10
8	Resistance to Soldering Heat (Reflow Soldering)	JEITA ED-4701 300 301	Tsol=250°C,10 sec Pre Treatment: 35 °C 95% RH96 Hrs	2 time, 10sec	10	0/10

The above test items such as differences or special customer specific requirements according to the actual situation in accordance with the requirements of customers to try the requirements with the customer, the customer is not required by our test standard test. Different products using different current test





5. Cautions

(1) Soldering Conditions

Number of reflow process shall be less than 2 times and cooling process to normal temperature is required between first and Second soldering process.

(Recommended soldering conditions)

Reflow Soldering			手工焊接		
Pre-heat Pre-heat time Peak temperature Soldering time Condition	Lead Solder 140 ~ 160° C 120 sec. Max. 230° C Max. 10 sec. Max.	Lead-free Solder 180 ~ 200° C 120 sec. Max. 240° C Max. 10 sec. Max.	Temperature Soldering time	350° C Max. 3 sec. Max. (one time only)	
(Lead	Solder)		(Lead-Free Solder)		
	10 SPC MOX.	Δ Δ Δ Δ Δ Δ Δ Δ Δ Δ Δ Δ Δ Δ	4°C /sec max.	- <u>-</u>	
Recommended Sold (Units : mm)	ering Patter	.8 0.	800		





(2) Static Electricity

It is recommended that a wrist band or an anti-electrostatic glove be used when handling the LEDs.

All devices, equipment and machinery must be properly grounded.

Damaged LEDs will show some unusual characteristics such as the forward voltage becomes lower, or

the LEDs do not light at the low current. Criteria : (VF > 2.0V at IF=0.5mA)

- (3) Moisture Proof Package
- It is recommended that moisture proof package be used.
- (4) Cautions:
 - 4.1. Please check if there is air leak before opening the package, if so, please return the goods back to take drying process for later using.
 - 4.2 Products can be used within 15days after packaging, after that, they must be:
 - 4.2.1 Soldered within 24 hrs
 - 4.2.2 Used in the condition: 30° C within and 60%RH below
 - 4.2.3 Stored in 30% RH for moisture below.
 - 4.3. Products cannot be used for and over 15days after being packaged unless opening the package and take drying our process in 85°C/6H.

4.4. Products not be used for or over 60days after being packaged please return back to take drying out and packaging process for forward using.

4.5. Products not be used after opening the package need to be dried out for 85° C/6H





PACKAGING

The LEDs are packed in cardboard boxes after taping.

